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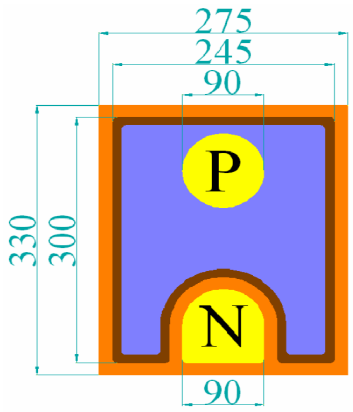
Data Sheet

LED Chip green — EOLC-515-35 — Rev. 02, 2017

Radiation	Type	Electrodes
green	InGaN/GaN	P + N up



Description

- Chip size: 330±20 µm x 275±20 µm (13 x 11 mil)
- P-bonding pad: Ø90±10 µm, thickness 2±0.2 µm, Au
- N-bonding pad: Ø90±10 µm, thickness 2±0.2 µm, Au
- Chip thickness: 90±10 µm

Maximum Ratings

T_{amb}= 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward current (DC)		I_F			30	mA
Peak forward current	$t_p \leq$ 50 µs, t_p/T=½	I_{FM}			100	mA

Optical and Electrical Characteristics

T_{amb}= 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	I_F=1 µA	V_F	1.7			V
Forward voltage	I_F=20 mA	V_F	2.8		3.8	V
Reverse current	V_R=8 V	I_R			0.5	µA
Dominant wavelength	I_F=20 mA	λ_D		515		nm
Luminous intensity	I_F=20 mA	Iv	485		530	mcd

*Measured on bare chip on TO-18 header

Packing

Chips on adhesive film with wire-bond side top

Art. No. 112 132

RoHS COMPLIANT Pb Pb-Free